

Title (en)  
METHOD FOR PRODUCING AN ELECTRONIC MODULE HAVING AN INTERLOCKINGLY CONNECTED HOUSING PART ELEMENT

Title (de)  
VERFAHREN ZUM HERSTELLEN EINES ELEKTRONIKMODULS MIT FORMSCHLÜSSIG ANGESCHLOSSENEM GEHÄUSETEILELEMENT

Title (fr)  
PROCÉDÉ PERMETTANT DE FABRIQUER UN MODULE ÉLECTRONIQUE POURVU D'UN ÉLÉMENT DE PARTIE DE BOÎTIER RACCORDÉ PAR COOPÉRATION DE FORMES

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Application  
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Abstract (en)  
[origin: WO2015090711A1] The invention relates to a method for producing an electronic module, wherein a circuit board element (1) is provided and a housing part element (15) is arranged on the circuit board element (1). The housing part element (15) is first separately produced and prepared. The housing part element (15) is formed by a material that can be reversibly plasticised, for example a thermoplastic such as polyamide. At least one portion (18) of a surface of the housing part element (15) is then reversibly plasticised, for example by means of local heating, in particular by irradiating with light. The housing part element (15) is then arranged on the circuit board element (1) by joining the plasticised portion of the surface of the housing part element to a microstructured portion (7) of the circuit board element and subsequently hardening the plasticised portion (18). Thus, an interlocking and hermetically sealed connection is formed between the housing part element (15) and the circuit board element (1).

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